IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower	level p	arts, the	declaratio	n encomp	asses all lov		erials for	which th	item is an assembly e manufacturer has eclaration.
Company Name * Company Unique ID Unique ID Authority Response Date * 2013-03-18 Contact Name * Title - Contact Phone - Contact * Email - Contact * reader @semtech.com Authorized Representative * Title - Representative Phone - Representative * Email - Representative * Title - Representative Phone - Representative * Email - Representative * Supplier Comments or URL for Additional Information Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight * UOM Unit Type RClamp1255P.TGT Low Capacitance RClamp Surge China 6.183 mg Each Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Nickel/Palladium/Gold (Ni/Pd/Au) 1 260 C 30 seconds 3	1752-2 1.1		:-1752 Standard												
SEMTECH CORPORATION 00-847-9941 2013-03-18 Contact Name * Title - Contact Phone - Contact * Freader @semtech.com Publicate Contact -> Authorized Representative Authorized Representative * Title - Representative Phone - Representative * Freader @semtech.com Phone - Representative * Freader @semtech.com Phone - Representative * Supplier Comments or URL for Additional Information reader @semtech.com Phone - Representative * Freader @semtech.com Phone - Representative * Freader @semtech.com Phone - Representative * Supplier Comments or URL for Additional Information Phone Phone - Representative * Freader @semtech.com Phone - Representative * Phone - Representative * Supplier Comments or URL for Additional Information Process Information Phone Phone - Representative * Phone - Representative * Supplier Comments or URL for Additional Information Process Phone Phone - Representative * Phone - Representative * Supplier Comments or URL for Additional Information Process Phone Phone - Representative * Phone - Repres	Supplier Information														
Contact Name * Title - Contact Phone - Contact * Roya Reader QA Customer Service Specialis 805-389-2742 reader @semtech.com Authorized Representative * Title - Representative Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 reader @semtech.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight * UOM Unit Type RClamp1255P.TGT Low Capacitance RClamp Surge China 6.183 mg Each Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy 1 260 C 30 seconds 3	Company Name *		Company Unique ID		Unique ID Au	uthority	Respo	nse Date	*	R	esponse Do	cument ID			
Roya Reader Authorized Representative * Title - Representative Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Phone - Representative * Roya Reader Phone - Representative * Roya Reader Phone - Representative * Representative * Roya Reader Phone - Roya Reader Phone - Represent	SEMTECH CORPORATION	ON	00-847-9941				2013-0	03-18							
Roya Reader Authorized Representative * Title - Representative Phone - Representative * Roya Reader QA Customer Service Specialis 805-389-2742 Requester Item Number Mfr Item Number Mfr Item Number Effective Date Version Manufacturing Site Weight * UOM Unit Type RClamp1255P.TGT Low Capacitance RClamp Surge China 6.183 mg Each Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Nickel/Palladium/Gold (Ni/Pd/Au) 1 260 C 30 seconds 3	Contact Name *		Title - Contact		Phone - Con	itact *	Email	- Contac	t *		D !! (0 1 1	A (1		
Requester Item Number	Roya Reader QA Customer Service Specialis			805-389-274	rreader@semtech.com				Duplicate Contact -> Authorized Representative						
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight * UOM Unit Type RClamp1255P.TGT Low Capacitance RClamp Surge China 6.183 mg Each Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy 1 260 C 30 seconds 3	Authorized Representative * Title - Representative			Phone - Representative *			Email - Representative *			Supplier Comments or URL for Additional Information					
RClamp1255P.TGT Low Capacitance RClamp Surge China 6.183 mg Each Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy Low Capacitance RClamp Surge China 6.183 mg Each Alternate Item Comments Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle 30 seconds 3	Roya Reader		QA Customer Service	e Specialis	805-389-274	2	rreade	er@semte	ch.com						
Alternate Recommendation Manufacturing Process Information Terminal Plating / Grid Array Material	Requester Item Number	r	Mfr Item Number		Mfr Item Name)	Effectiv	e Date	Version	Manufact	uring Site	Weight *	UC	M	Unit Type
Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy 1 260 °C 30 seconds 3			RClamp1255P.TGT		Low Capacita	nce RClamp Surg	e			China		6.183	mg	l	Each
Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base	Alternate Recommenda	ation							Alternate	Item Com	ments	•	•		•
Nickel/Palladium/Gold (Ni/Pd/Au) CU Alloy 1 260 C 30 seconds 3	Manufacturing Proces	ss In	formation												
	Terminal Plating / Grid Array	Materi	al	Terminal B	ase Alloy	J-STD-020 MSL Ra	ating	Peak Proc	ess Body	Temperat	ure Max Tim	e at Peak Tem	perature	Number o	f Reflow Cycles
Comments	Nickel/Palladium/Gold (Ni/Pd	//Au)	CU Alloy	,	1			;	260 C		30 s	econds	3	
Comments	Comments					1									

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type *** Detailed Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a ?RoHS restricted substance?) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier?s liability and the Company?s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply. 1 - Item(s) does not contain RoHS restricted substances per the definition above Supplier Acceptance * Accepted **RoHS Declaration *** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature**

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of			Level	Substance Category			Substance	CAS	Exempt	Woight	O O.	Tolera	nce	PPM
	Name		Material	weight	Measure			Levei	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	FFIVI
+1 -1	Die	+M -M	Doped Silicon	0.5204	mg	+C -	-C s	Supplier		+S	-s	Si	7440-21-3		0.5204	mg			84,159
+1 -1	Lead frame	+M -M	C7025	2.23587	mg	+C -	-C s	Supplier		+S	-S	Cu	7440-50-8		2.1442	mg		;	346,77
										+S	-s	Si	7440-21-3		0.0162	mg			2,622
						+C -	-С в	3		+S	-s	Nickel	7440-02-0		0.0715	mg			11,571
						+C -	-C s	Supplier		+S	-s	Mg	7439-95-4		0.0039	mg			633
		+M -M	Ni/Pd/Au plating	0.05733	mg	+C -	-С в	3		+S	-S	Nickel	7440-02-0		0.0517	mg			8,360
						+C -	-C s	Supplier	middle plating	+S	-s	Pd	7440-05-3		0.0047	mg			760
						+C -	-C s	Supplier	outer plating	+S	-s	Au	7440-57-5		0.0009	mg			151
+1 -1	Bonding wire	+M -M	CuAu	0.03945	2mg	+C	-C s	Supplier		+S	-s	Au	7440-57-5		0.0276	mg			4,466
										+S	-s	Cu	7440-50-8		0.0118	mg			1,914
+1 -1	Molding compound	+M -M	EME-G770HCD	3.08156	mg	+C	-C s	Supplier		+S	-s	Silica fused	60676-86-0		2.8813	mg			465,97
										+S	-s	Epoxy resin	proprietary		0.0924	mg			14,951
										+S	-s	Phenol resin	proprietary		0.0924	mg			14,951
										+S	-s	С	1333-86-4		0.0154	mg			2,492
+1 -1	Die attached adhes	+M -M	QMI519	0.23629	2mg	+C -	-C s	Supplier		+S	-S	Ag	7440-22-4		0.189	mg		;	30,571
										+S	-s	Palladium compound	proprietary		0.0004	mg			57
										+S	-s	2,6-Di-tert-butyl-p-creso	128-37-0		0.00001	mg			2
										+S	-s	Hydroquinone	123-31-9		0.000000	mg			0.03
										+S	-s	Acrylate	proprietary		0.0374	mg			6,055
										+S	-s	Bismaleimide resin	proprietary		0.0071	mg			1,146
										+S	-s	Polymer of polybutadie	proprietary		0.0024	mg			382
		+M -M	8006NS	0.01243	mg	+C	-C s	Supplier		+S	-S	Aluminum oxide	1344-28-1		0.0042	mg			684
										+S	-s	Diethylene glycol mono	112-15-2		0.0042	mg			684

+S	-S	Epoxy resins	proprietary	0.0035	mg		563
+S	-S	Amine	proprietary	0.0005	mg		80